



Material Content Data Sheet



Sales Product Name				IPI051N15N5		Issued		19. January 2018	
MA#				MA001327836					
Package				PG-TO262-3-1		Weight*		1587.77 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	7.046	0.44	0.44	4438	4438	
leadframe	non noble metal	iron	7439-89-6	0.851	0.05		536		
	inorganic material	phosphorus	7723-14-0	0.255	0.02		161		
	non noble metal	copper	7440-50-8	849.682	53.52	53.59	535140	535838	
wire	non noble metal	aluminium	7429-90-5	113.824	7.17	7.17	71688	71688	
encapsulation	organic material	carbon black	1333-86-4	7.324	0.46		4613		
	plastics	epoxy resin	-	80.568	5.07		50743		
	inorganic material	silicondioxide	60676-86-0	400.398	25.22	30.75	252176	307532	
leadfinish	non noble metal	tin	7440-31-5	15.198	0.96	0.96	9572	9572	
plating	non noble metal	nickel	7440-02-0	0.228	0.01		144		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	144	
solder	noble metal	silver	7440-22-4	0.151	0.01		95		
	non noble metal	tin	7440-31-5	0.121	0.01		76		
	non noble metal	lead	7439-92-1	5.776	0.36	0.38	3638	3809	
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		67		
	inorganic material	phosphorus	7723-14-0	0.032	0.00		20		
	non noble metal	copper	7440-50-8	106.210	6.69	6.70	66892	66979	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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